

Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL: NONE
- 3) Cu PADS DESIGNED FOR 0.635mm BALL ATTACH
- 4) SOLDER MASK DEFINED PAD OPENING: 0.508 [20 MIL].
- 5) PAD Cu DIAMETER: 0.685mm [27 MIL].
- 6) SUBSTRATE MATERIAL: FR4.
- 7) DUMMY DIE IS OPTIONAL. PIN A1 DOT.
- 8) FULL BUS PATTERN (ALL I/O CONNECTED).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

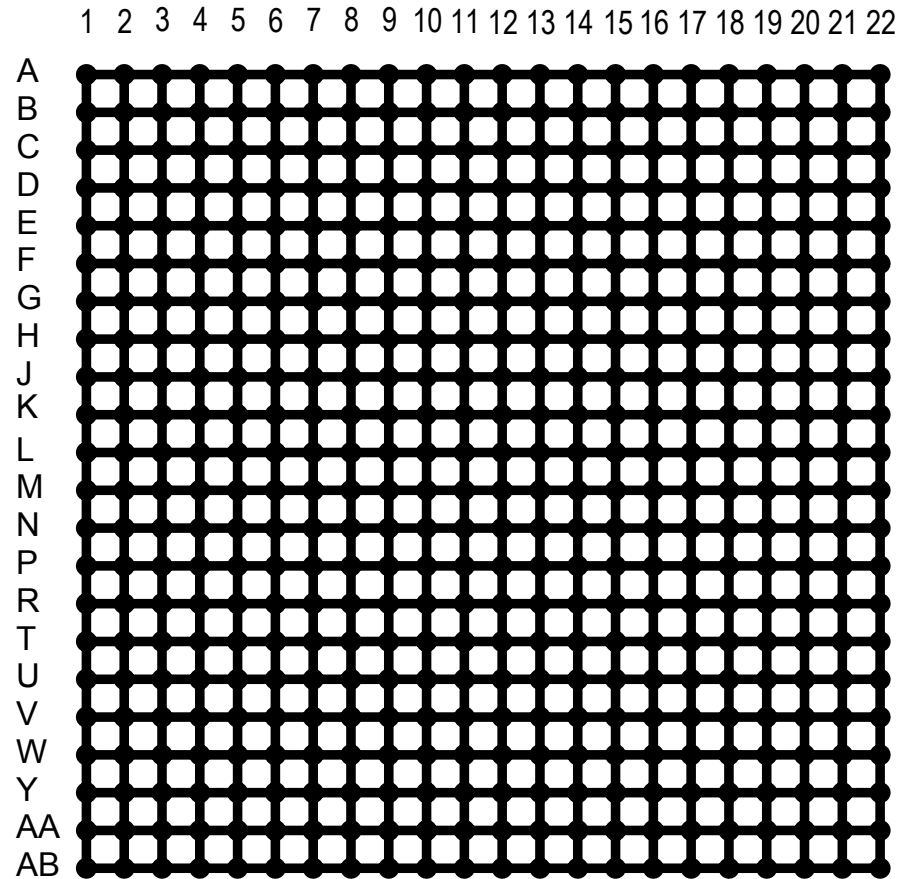
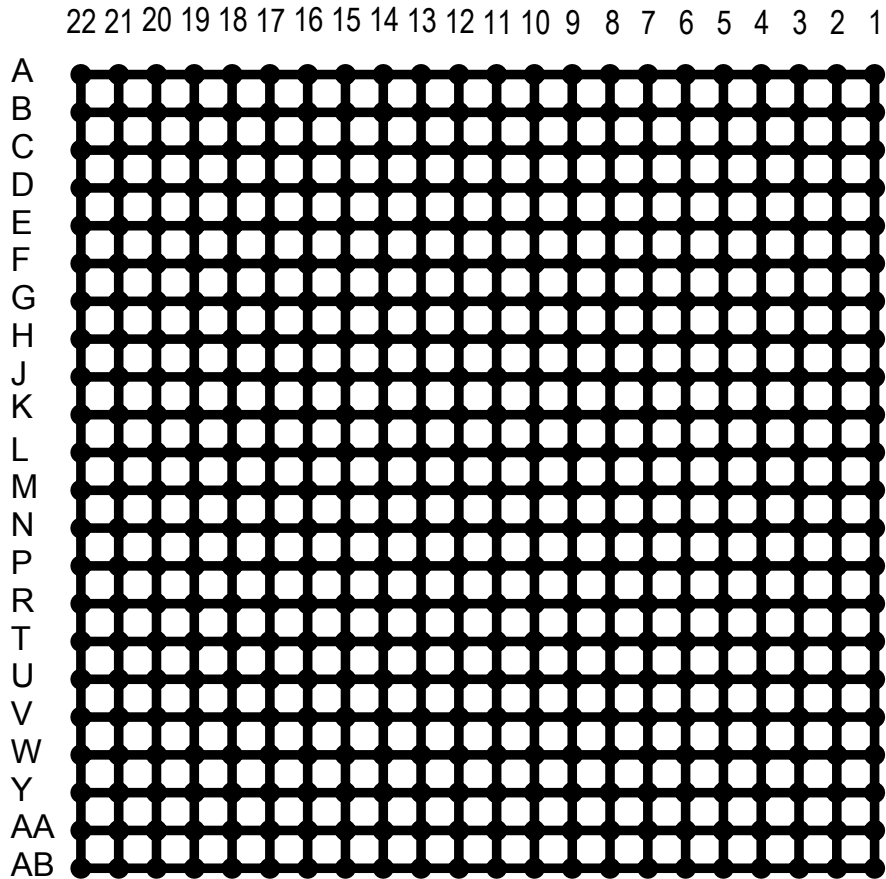
PART NUMBER TABLE

PART NUMBER WITHOUT DIE	PART NUMBER WITH DUMMY DIE	PAD FINISH	PAD TYPE	RoHS
LGA324T1.0Sn-BUS	LGA324T1.0Sn-BUS-D	Tin - Sn	SMD	YES
LGA324T1.0Cu-BUS	LGA324T1.0Cu-BUS-D	OSP - Cu	SMD	YES
LGA32T1.0G-BUS	LGA32T1.0G-BUS-D	ENIG (GOLD) Ni/Au	SMD	YES

APPROVALS		DATE				
DRAWN	T. Au	12/21/12				
ENG	M. Hart	12/21/12	TITLE LGA324T1.0-BUS BUS CIRCUIT DUMMY			
MFG						
QA			SCALE	SIZE	DRAWING NO.	REV
CUST				A	512208	A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 2

BALL VIEW

BOTTOM SIDE (TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.685mm [27 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.203mm [8 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.508mm [20 MIL].

TopLine®			
TITLE		LGA324T1.0-BUS BUS CIRCUIT DUMMY	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	512208	A
DO NOT SCALE DRAWING			SHEET 2 OF 2